

ABSTRACT

This document describes the known exceptions to the functional specifications (advisories).

Table of Contents

1 Functional Advisories	1
2 Preprogrammed Software Advisories	2
3 Debug Only Advisories	
4 Fixed by Compiler Advisories	
5 Device Nomenclature	
6 Advisory Descriptions	
7 Revision History	
,	

Trademarks

All trademarks are the property of their respective owners.

1 Functional Advisories

Advisories that affect the device's operation, function, or parametrics.

 \checkmark The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev A
ADC_ERR_05	✓
I2C_ERR_05	✓
I2C_ERR_06	✓
PMCU_ERR_07	✓
PMCU_ERR_10	✓
SPI_ERR_04	✓
SPI_ERR_05	✓
SYSOSC_ERR_01	√
SYSOSC_ERR_02	✓
TIMER_ERR_04	✓
TIMER_ERR_06	✓
VREF_ERR_03	√

1



2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

 \checkmark The check mark indicates that the issue is present in the specified revision.

3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev A
GPIO_ERR_03	\checkmark

4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

5 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

XMS - Experimental device that is not necessarily representative of the final device's electrical specifications

MSP – Fully qualified production device

Support tool naming prefixes:

X: Development-support product that has not yet completed Texas Instruments internal qualification testing. Please note that X marked development samples should be operated in -40°C to 85°C temperature range.

null: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

6 Advisory Descriptions

ADC_ERR_05	ADC Module	
Category	Functional	
Function	HW Event generated before enabling IP, ADC Trigger will stay in queue	
Description	When ADC is configured in HW event trigger mode and the trigger is generated before enabling the ADC, the ADC trigger will stay in queue. Once ADC is enabled, it will trigger sampling and conversion.	
Workaround	After configuring ADC in HW trigger mode, enable ADC first before giving external trigger.	
GPIO_ERR_03	GPIO and DEBUGSS Module	
Category	Debug only	
Function	On a debugger read to GPIO EVENT0 IIDX, interrupt is cleared.	
Description	EVENT0's IIDX of GPIO, on a debugger read is treated as a CPU read and interrupt is getting cleared.	
Workaround	In case GPIO interrupts and events are expected, do not read using IIDX register via the debugger. Instead, utilize a software read of RIS register.	
I2C_ERR_05	I2C Module	
Category	Functional	
Function	I2C SDA may get stuck to zero if we toggle ACTIVE bit during ongoing transaction	
Description	If ACTIVE bit is toggled during an ongoing transfer, its state machine will be reset. However, the SDA and SCL output which is driven by the master will not get reset. There is a situation where SDA is 0 and master has gone into IDLE state, here the master won't be able to move forward from the IDLE state or update the SDA value. Slave's BUSBUSY is set (toggling of the ACTIVE bit is leading to a start being detected on the line) and the BUSBUSY won't be cleared as the master will not be able to drive a STOP to clear it.	
Workaround	Do not toggle the ACTIVE bit during an ongoing transaction.	
I2C_ERR_06	I2C Module	
Category	Functional	



I2C_ERR_06 (continued)	lued) I2C Module	
Function		
Description	SMBus High timeout feature is failing at I2C clock rate less than 24KHz onwards (20KHz, 10KHz). From SMBUS Spec, the upper limit on SCL high time during active transaction is 50us. Total time taken from writing of START MMR bit to SCL low is 60us, which is >50us. It will trigger the timeout event and let I2C Master goes into IDLE without completing the transaction at the start of transfer itself. Below is detailed explanation. For SCL is configured as 20KHz, SCL low and high period is 30us and 20us respectively. First, START MMR bit write at the same time high timeout counter starts decrementing. Then, it takes one SCL low period (30us) from START MMR bit write to SDA goes low (start condition). Next, it takes another SCL low period (30us) from SDA goes low (start condition) to SCL goes low (data transfer starts) which should stop the high timeout counter at this point. As a total, it takes 60us from counter start to end. However, due to the upper limit(50us) of the high timeout counter, the timeout event will still be triggered although the I2C transaction is working fine without issue.	
Workaround	Do not use SMBus High timeout feature when I2C clock less than 24KHz onwards.	
PMCU_ERR_07	PMCU Module	
Category	Functional	
Function	NRST<1sec pulse giving wrong rstcause in shutdown mode	
Description	The rstcause value is wrong under the following condition. Though the expected rstcause is 0x05. (i) Device is configured for shutdown mode (ii) WFI() is called (iii) Give NRST<1sec pulse to bring device out from shutdown mode	
Workaround	No workaround.	
PMCU_ERR_10	PMCU Module	
Category	Functional	
Function	VBOOST might have larger delay under certain operating conditions	
Description	VBOOST for analog MUX has large delay at VDD<1.8V, which delays settling time of other modules like HFXT, COMP, SYSOSC(FCL-external R),OPA and GPAMP.	
Workaround	Keep VDD>=1.8V and use VBOOST in ONALWAYS mode using GENCLKCFG[23:22]=0x2.	

SPI_ERR_04	SPI Module	
Category	Functional	
Function	IDLE/BUSY status toggle after each frame receive when SPI peripheral is in only receive mode.	
Description	In case of SPI peripheral in only receiving mode, the IDLE interrupt and BUSY status are toggling after each frame receive while SPI is receiving data continuously(SPI_PHASE=1). Here there is no data loaded into peripheral(slave) TXFIFO and TXFIFO is empty.	
Workaround	Do not use SPI peripheral only receive mode. Set SPI in peripheral(slave) simultaneous transmit and receive mode.	
SPI_ERR_05	SPI Module	
Category	Functional	
Function	SPI Peripheral Receive Timeout interrupt is setting irrespective of RXFIFO data	
Description	When using SPI timeout interrupt, the RXTIMEOUT counter started decrementing from the point that peripheral is stopped receiving SPI clock and setting the RXTIMEOUT interrupt irrespective of data exists in RXFIFO or not, which does not match the description in the TRM: SPI peripheral receive timeout(RTOUT) interrupt is "asserted when the receive FIFO is not empty, and no further data is received in the specified time at CTL1.RXTIMEOUT.	
Workaround	Repeat load RXTIMEROUT counter value while receive FIFO is empty, and start timeout counting only when receive FIFO gets any data.	
SYSOSC_ERR_01	01 SYSOSC Module	
Category	Functional	
Function	MFCLK drift when using SYSOSC FCL together with STOP1 mode	
Description	IF MFCLK is enabled AND SYSOSC is using the frequency correction loop (FCL) mode AND the STOP1 low power operating mode is used, THEN the MFCLK may drift by two cycles when SYSOSC shifts from 4MHz back to 32MHz (either upon exit from STOP1 to RUN mode or upon an asynchronous fast clock request that forces SYSOSC to 32MHz).	
Workaround		
	Use STOP0 mode instead of STOP1 mode. There is no MFCLK drift when STOP0 mode is used.	



SYSOSC_ERR_01 (continued)

SYSOSC Module

OR

Do not use SYSOSC in the FCL mode (leave FCL disabled) when using STOP1.

SYSOSC_ERR_02	2 SYSOSC Module	
Category	Functional	
Function	MFCLK fails to start up in certain conditions.	
Description	MFCLK will not start to toggle in the below scenario:	
	1. FCL mode is enabled and then MFCLK is enabled	
	2. Enter a low power mode where SYSOSC is disabled (SLEEP2/STOP2/STANDBY0/ STANBY1).	
	3. Now asynchronous clock request is received from some peripheral which uses MFCLK as its functional clock.	
Workaround	Avoid the above scenario - check that your system does not use FCL and MFCLK along with the listed low power modes while asynchronous fast clock requests are enabled.	
TIMER_ERR_04	TIMER Module	
Category	Functional	
Function	TIMER re-enable may be missed if done close to zero event	
Description	When using a GPTIMER in one shot mode and CLKDIV.RATIO is not 0, TIMER re-enable may be missed if done close to zero event.	
Workaround	TIMER can be disabled first before re-enabling.	

7



TIMER_ERR_06	Timer module	
Category	Functional	
Function	Writing 0 to CLKEN does not disable the counter.	
Description	Writing 0 to the Counter Clock Control (CCLKCTL) Clock Enable bit (CLKEN) does not stop the timer.	
Workaround	Stop the timer by writing 0 to the Counter Control(CTRCTL) Enable(EN) bit.	
VREF_ERR_03		
Category	Functional	
Function	Vref Module will turn off when in standby mode when COMP is also active	
Description	When using the COMP and internal VREF in STANDBY mode, the VREF module will turn off.	
Workaround	Use COMP and internal VREF in STOP2 Mode.	

7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
December 2024	*	Initial Release

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2024, Texas Instruments Incorporated